

## REMARKS

### Arrangement of the Specification

The Office Action requested that Applicant add a "Summary of the Invention" description to the application. However, Applicant would like to kindly point out that neither the M.P.E.P. nor 37 C.F.R. §1.73 require the presence of a "Summary of the Invention" in a patent application. They merely indicate where in the application the "Summary of the Invention" should be placed if Applicant were to elect to include one.

In particular, 37 C.F.R. §1.73 only states that "[a] brief summary of the invention ... should precede the detailed description." 37 CFR § 1.73 does not state "must" or "shall." Accordingly, Applicant has elected not to include a "Summary of the Invention" as this is within the discretion of Applicant.

### Claim Objections

The Examiner objected to claims 28-35, contending that the word "solid" is not described nor supported in the specifications. The word "solid" appears in Paragraph [0010], line 8. Applicant, accordingly, respectfully requests withdrawal of the objection to claims 28-35 under this heading.

### 35 U.S.C. § 112 Rejections

The Examiner has rejected claims 32-35 under 35 U.S.C. § 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the art that the inventor(s) at the time that the application was filed, had possession of the claimed invention.

Specifically, the Examiner contends that there is no support for “bonding a side of the monocrystalline semiconductor material through which the ions are implanted to the layer of material.” In Figure 2C, a side of a monocrystalline silicon wafer 56 is implanted with ions 58. In Figure 2E, the side which is implanted with the ions is bonded to the polysilicon layer 54. There is thus clearly support for the section of the claim that the Examiner objected to.

The Examiner also stated that there is no support for severing a portion of the semiconductor material from a portion “that is bonded to the layer of material.” This is clearly illustrated by comparing Figures 2G and 2H, wherein the monocrystalline silicon wafer 56A is severed from the final monocrystalline silicon film 56B. There is thus clearly support for the section of the claim that the Examiner objected to.

Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 32-35 under 35 U.S.C. § 112, first paragraph.

### 35 U.S.C. § 102 Rejections

The Examiner has rejected claims 28-29 under 35 U.S.C. § 102(b) as being anticipated by Ravi. Claim 29 has been cancelled. Applicant submits that claim 28, as amended, is not anticipated by Ravi.

Ravi discloses linear processing of a wafer. Layers are successively added and subtracted from a combination wafer. At no stage are there two separate wafers processed in parallel, and at no stage is one wafer attached to another wafer. Ravi thus fails to teach or suggest the formation of a first combination wafer, the formation of a second combination wafer, and the formation of a third combination wafer by attaching the first combination wafer to the second combination wafer.

Claim 28 now specifically includes the limitations of forming a first combination wafer, forming a second combination wafer, and forming a third combination wafer by attaching the first combination wafer to a component of the second combination wafer. Specifically, the first combination wafer has a support layer and a layer of solid diamond on the support layer, the second combination wafer is formed by implanting ions into a surface of a monocrystalline semiconductor material, and third combination wafer is formed by attaching the first combination wafer to the second combination wafer.

Claim 28 thus includes at least one limitation that is not suggested by Ravi. Claim 28 is thus not anticipated by Ravi. Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 28 under 35 U.S.C. § 102(b) as being anticipated by Ravi.

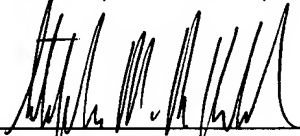
The Examiner rejected claim 31 as being anticipated by Clevenger. Claim 31 has been cancelled without prejudice.

Applicant respectfully submits that the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Stephen M. De Klerk at (408) 720-8300.

Please charge any shortages and credit any overages to Deposit Account No. 02-2666. Any necessary extension of time for response not already requested is hereby requested. Please charge any corresponding fee to Deposit Account No. 02-2666.

Respectfully submitted,

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Date: November 15, 2004

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